



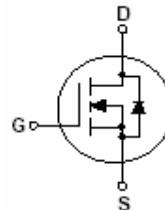
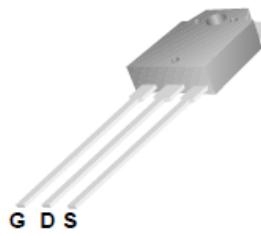
# Wisdom Technologies Int'l

## WFW20N60

**600V N-Channel MOSFET**

### Features

- Low Intrinsic Capacitances
- Excellent Switching Characteristics
- Extended Safe Operating Area
- Unrivalled Gate Charge :98 nC (Typ.)
- BVDSS=600V, ID=20A
- Lower  $R_{DS(on)}$  : 0.45Ω (Max) @VG=10V
- 100% Avalanche Tested



TO-3P

G-Gate,D-Drain,S-Source

### Absolute Maximum Ratings $T_c=25^\circ C$ unless otherwise noted

Symbol	Parameter	WFW20N60	Units
$V_{DSS}$	Drain-Source Voltage	600	V
$I_D$	Drain Current -continuous ( $T_c=25^\circ C$ )	20	A
	-continuous ( $T_c=100^\circ C$ )	12.7	A
$V_{GS}$	Gate-Source Voltage	$\pm 30$	V
$E_{AS}$	Single Plused Avalanche Energy (Note1)	690	mJ
$I_{AR}$	Avalanche Current (Note2)	20	A
$P_D$	Power Dissipation ( $T_c=25^\circ C$ )	208	W
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 ~ +150	°C
TL	Maximum lead temperature for soldering purpose, 1/8" from case for 5 seconds	300	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max	Units
$R_{\theta JC}$	Thermal Resistance,Junction to Case	--	0.48	°C/W
$R_{\theta JA}$	Thermal Resistance,Junction to Ambient	--	41.7	°C/W

**Electrical Characteristics T<sub>c</sub>=25°C unless other wise noted**

Symbol	Parameter	Test Condition	Min.	Typ.	Max	Units
<b>Off Characteristics</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	ID=250 μ A, VGS=0	600	--	--	V
△BV <sub>DSS</sub> / △T <sub>J</sub>	Breakdown Voltage Temperature Conficient	I <sub>D</sub> =250 μ A, Reference to 25°C	--	0.6	--	V/°C
IDSS	Zero Gate Voltage Drain Current	Vds=600V, Vgs=0V	--	--	1	μ A
		Vds=480V, T <sub>c</sub> =125°C			10	μ A
IGSSF	Gate-body leakage Current, Forward	Vgs=+30V, Vds=0V	--	--	100	nA
IGSSR	Gate-body leakage Current, Reverse	Vgs=-30V, Vds=0V	--	--	-100	nA

**On Characteristics**

V <sub>GS(th)</sub>	Date Threshold Voltage	I <sub>d</sub> =250uA, V <sub>ds</sub> =V <sub>gs</sub>	2	--	4	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	I <sub>d</sub> =10A, V <sub>gs</sub> =10V	--	--	0.3	Ω

**Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	VDS=25V, VGS=0, f=1.0MHz	--	1730	2250	pF
C <sub>oss</sub>	Output Capacitance		--	960	1150	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	85	--	pF

**Switching Characteristics**

T <sub>d(on)</sub>	Turn-On Delay Time	VDD=300V, ID=20A, RG=25 Ω (Note 3,4)	--	46	90	nS
T <sub>r</sub>	Turn-On Rise Time		--	140	280	nS
T <sub>d(off)</sub>	Turn-Off Delay Time		--	175	350	nS
T <sub>f</sub>	Turn-Off Fall Time		--	100	200	nS
Q <sub>g</sub>	Total Gate Charge	VDS=480, VGS=10V, ID=20A (Note 3,4)	--	57	72	nC
Q <sub>gs</sub>	Gate-Source Charge		--	11.5	14	nC
Q <sub>gd</sub>	Gate-Drain Charge		--	28	--	nC

**Drain-Source Diode Characteristics and Maximum Ratings**

I <sub>s</sub>	Maximum Continuous Drain-Source Diode Forward Current	--	--	20	A	
I <sub>SM</sub>	Maximum Plused Drain-Source DiodeForwad Current	--	--	60	A	
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	I <sub>d</sub> =20A	--	--	1.4	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>s</sub> =20A, V <sub>GS</sub> =0V	--	450	--	nS
Q <sub>rr</sub>	Reverse Recovery Charge	di <sub>f</sub> /dt=100A/ μ s (Note3)	--	8.2	--	μ C

\*Notes 1, L=3.2mH, IAS=20.0A, VDD=50V, RG=25Ω, Starting TJ =25°C

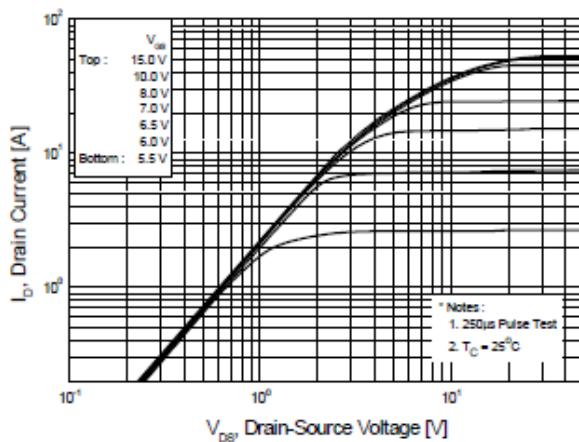
2, Repetitive Rating : Pulse width limited by maximum junction temperature

3, Pulse Test : Pulse Width ≤ 300μs, Duty Cycle ≤ 2%

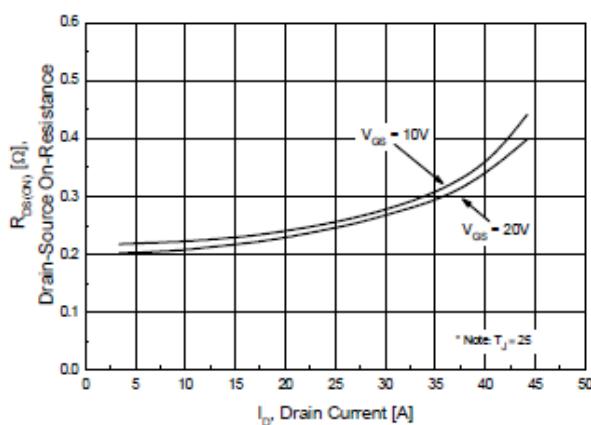
4, Essentially Independent of Operating Temperature

## Typical Characteristics

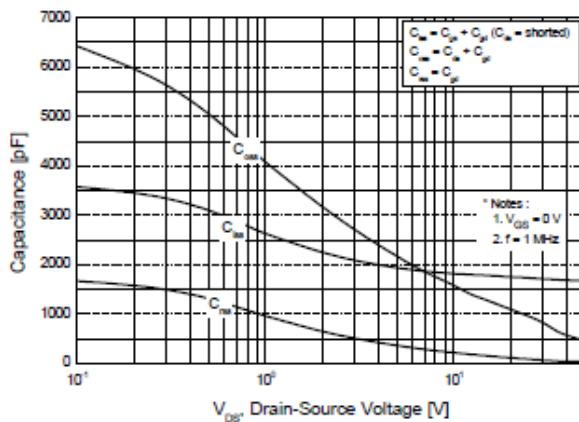
**Figure 1. On-Region Characteristics**



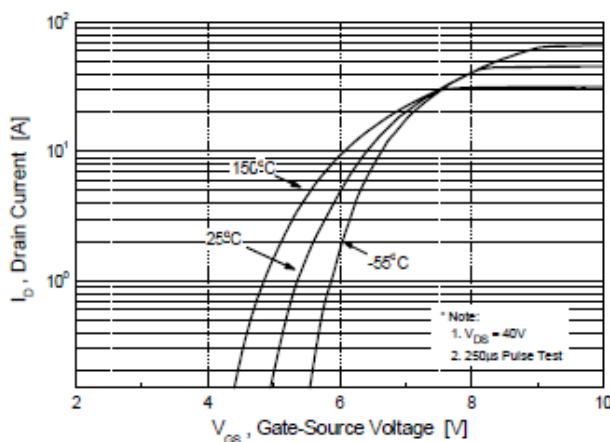
**Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage**



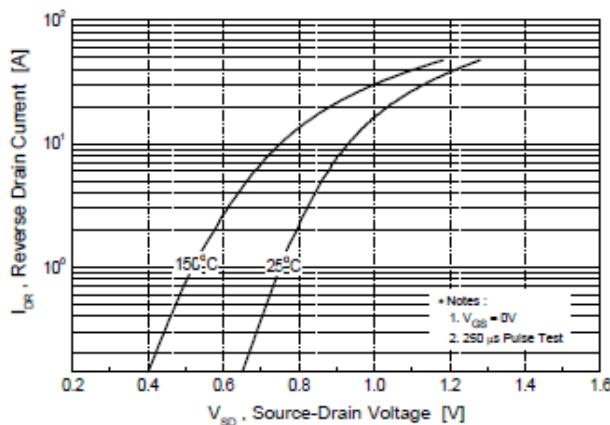
**Figure 5. Capacitance Characteristics**



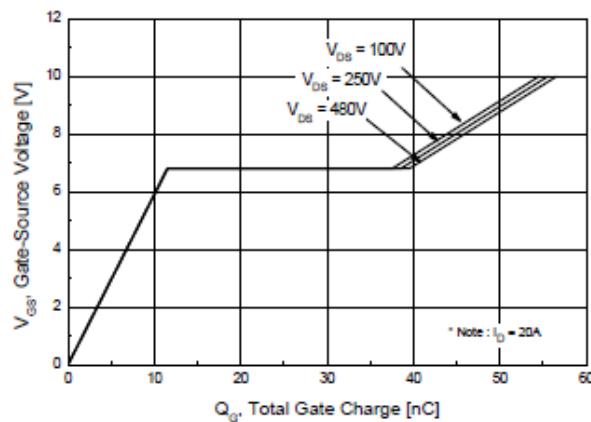
**Figure 2. Transfer Characteristics**



**Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature**

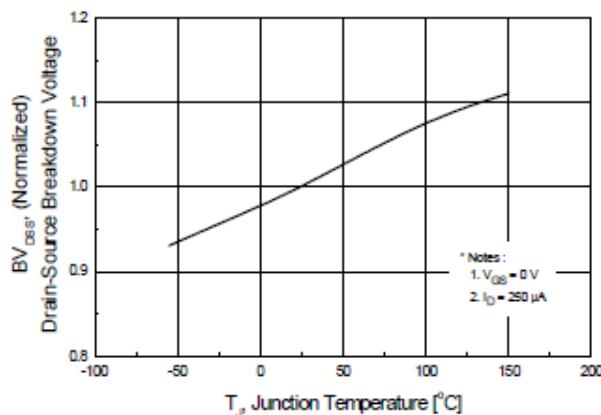


**Figure 6. Gate Charge Characteristics**

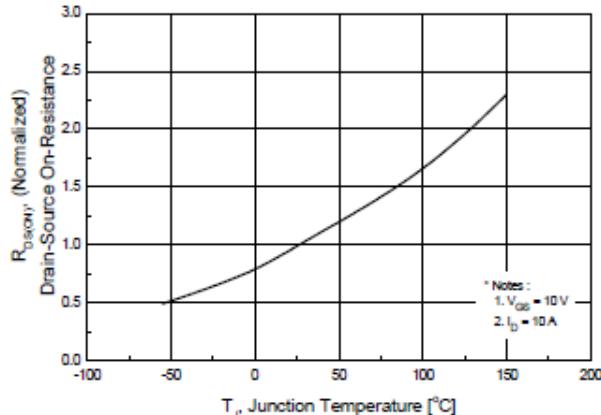


## Typical Characteristics (Continued)

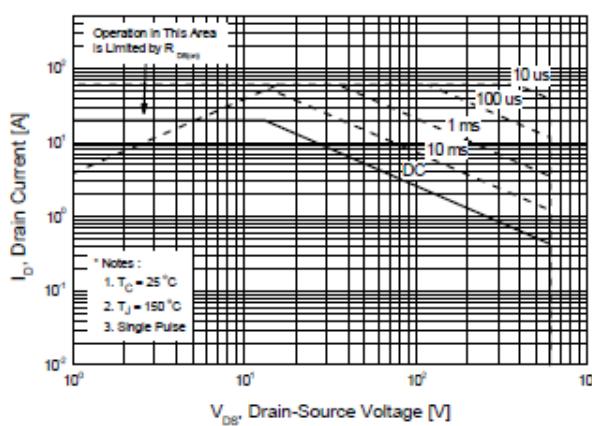
**Figure 7. Breakdown Voltage Variation vs. Temperature**



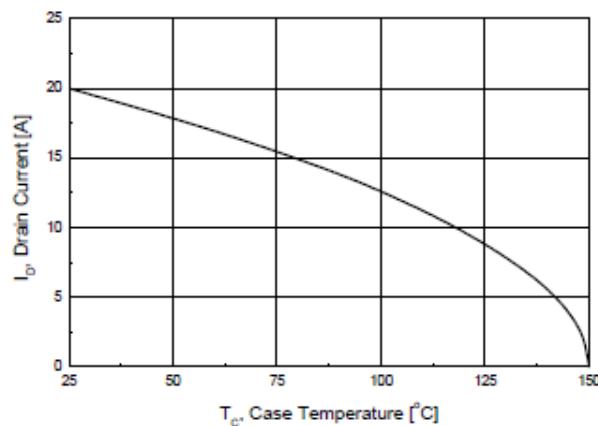
**Figure 8. On-Resistance Variation vs. Temperature**



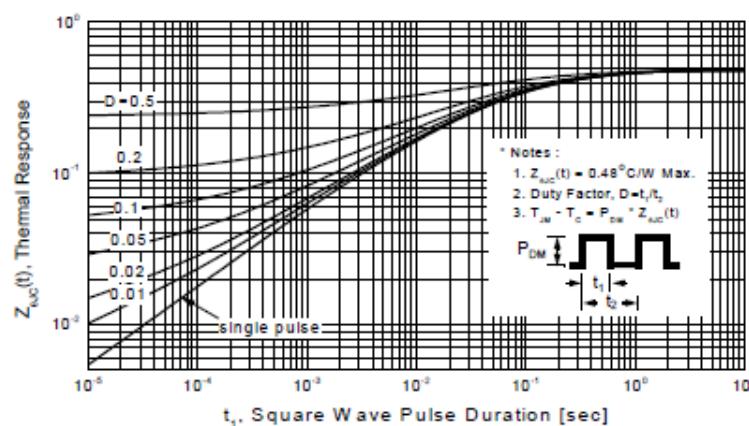
**Figure 9. Maximum Safe Operating Area**

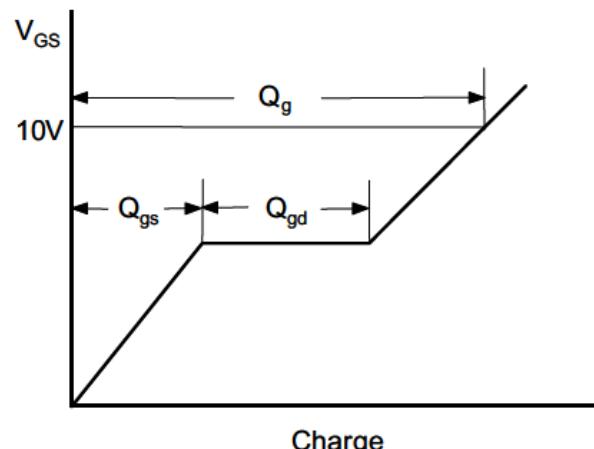
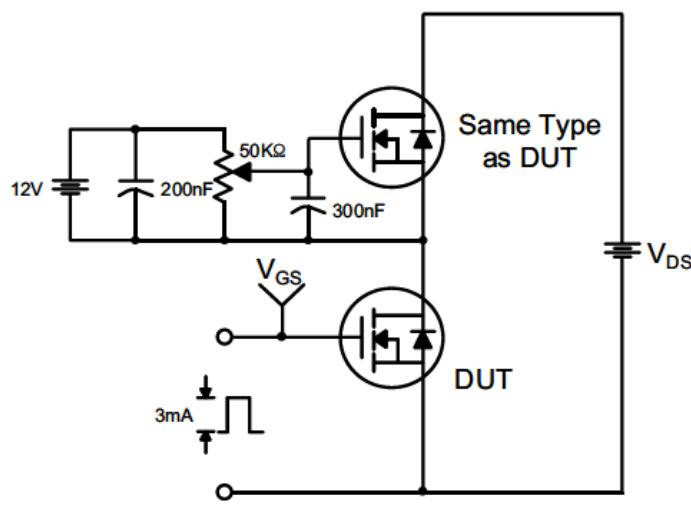
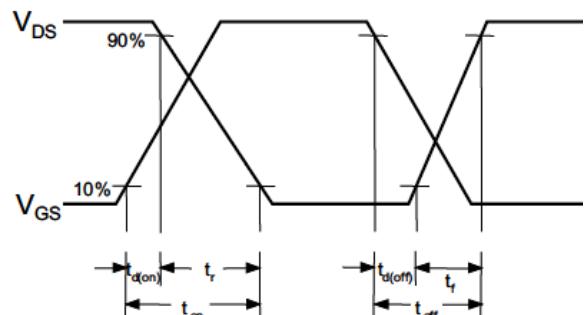
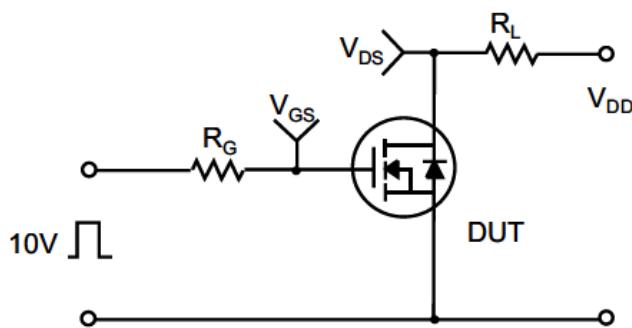
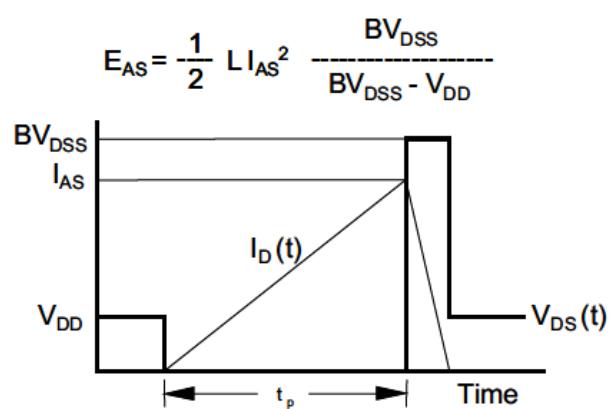
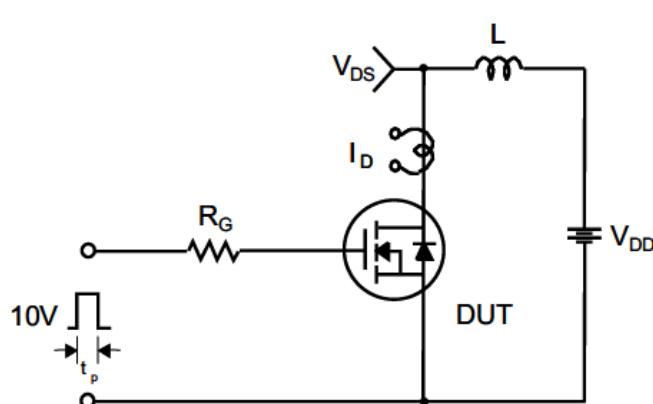


**Figure 10. Maximum Drain Current vs. Case Temperature**

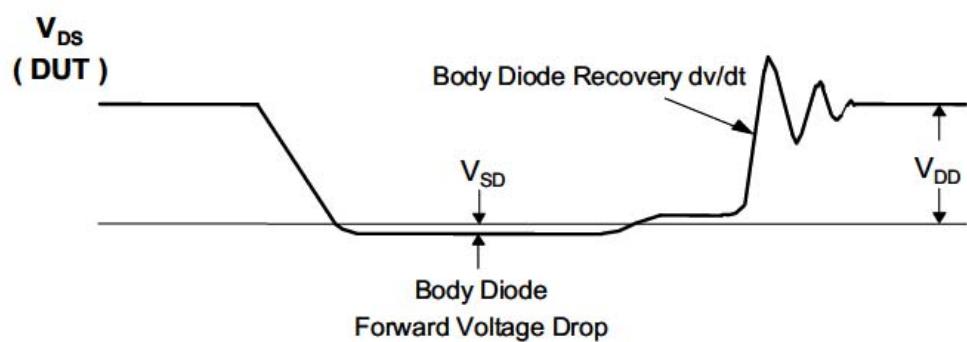
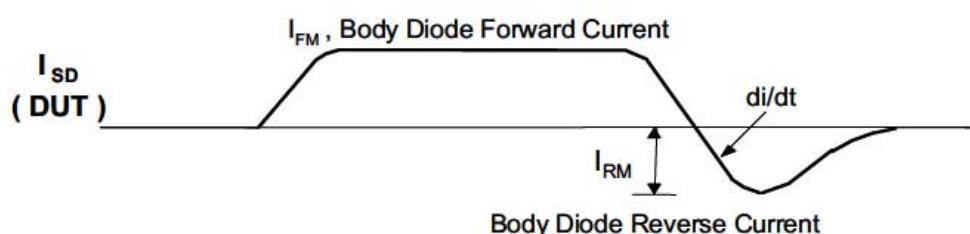
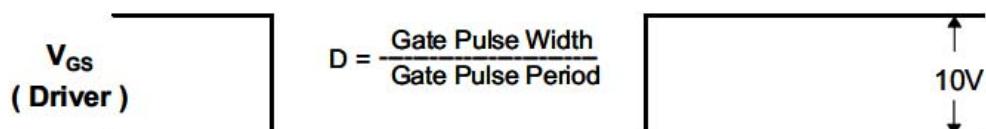
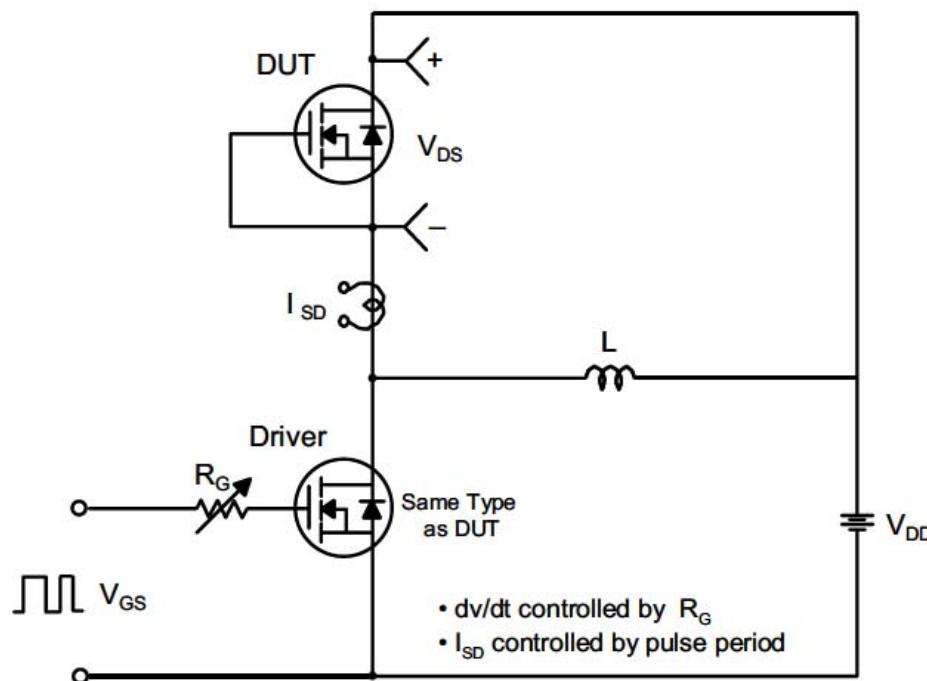


**Figure 11. Transient Thermal Response Curve**



**Gate Charge Test Circuit & Waveform**

**Resistive Switching Test Circuit & Waveforms**

**Unclamped Inductive Switching Test Circuit & Waveforms**


## Peak Diode Recovery dv/dt Test Circuit &amp; Waveforms



## Package Dimension

TO-3P

